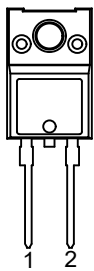
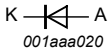


[illegible]

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$Q_r$	recovered charge	$I_F = 6\text{ A}$ ; $di_F/dt = 500\text{ A}/\mu\text{s}$ ; $V_R = 400\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>		-	10	-	nC

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO220F-2L</p>	 <p>001aaa020</p>
2	A	anode		
mb	n.c.	mounting base; isolated		

## 6. Ordering information

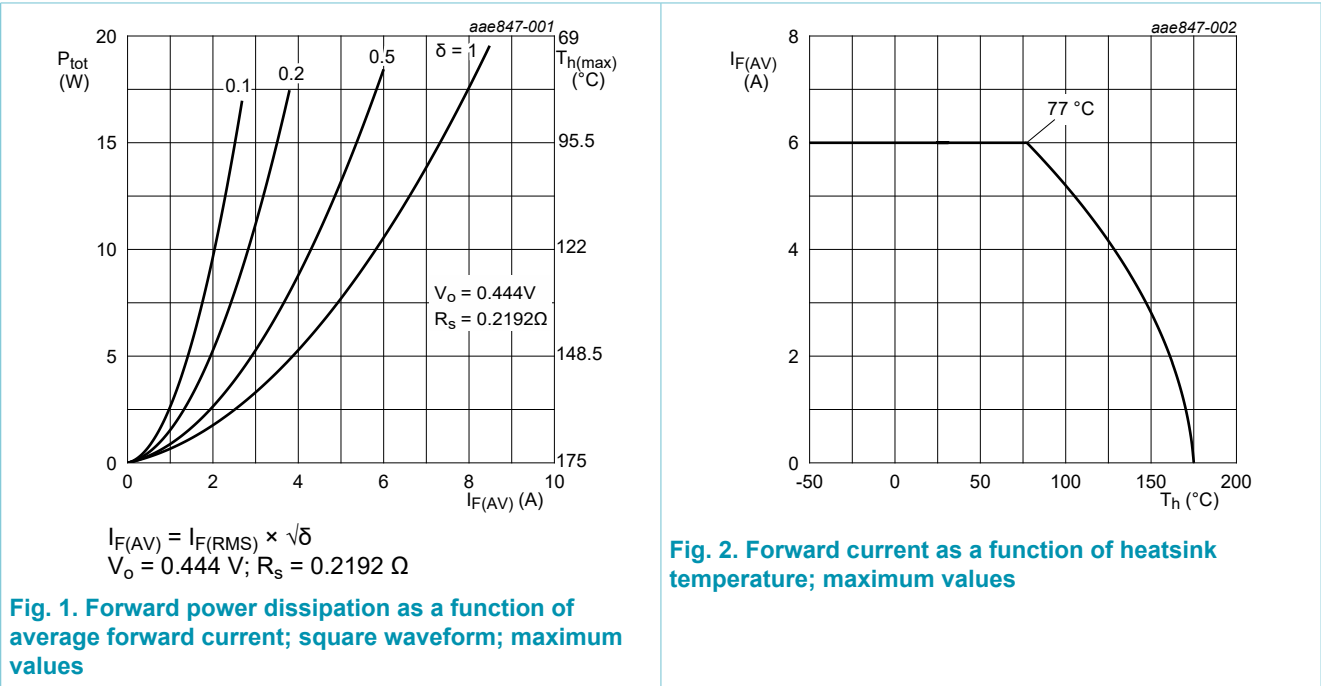
Table 3. Ordering information

Type number	Package		
	Name	Description	Version
NXPSC06650X	-	Plastic single-ended through-hole package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220F	TO220F-2L

7. Limiting values

Table 4. Limiting values  
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>RRM</sub>	repetitive peak reverse voltage		-	650	V
V <sub>RWM</sub>	crest working reverse voltage		-	650	V
V <sub>R</sub>	reverse voltage	DC	-	650	V
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; T <sub>h</sub> ≤ 77 °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3; Fig. 4	-	6	A
I <sub>FRM</sub>	repetitive peak forward current	δ = 0.5 ; t <sub>p</sub> = 25 μs; T <sub>h</sub> ≤ 77 °C; square-wave pulse	-	12	A
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 10 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse	-	36	A
		t <sub>p</sub> = 10 μs; T <sub>j(init)</sub> = 25 °C; square-wave pulse	-	310	A
T <sub>stg</sub>	storage temperature		-55	175	°C
T <sub>j</sub>	junction temperature		-	175	°C



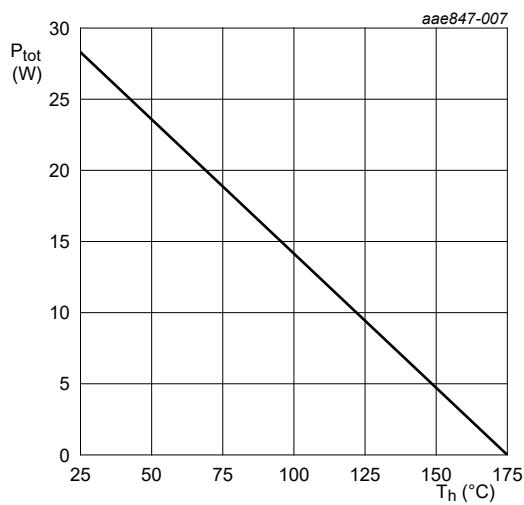


Fig. 3. Total power dissipation as a function of heatsink temperature

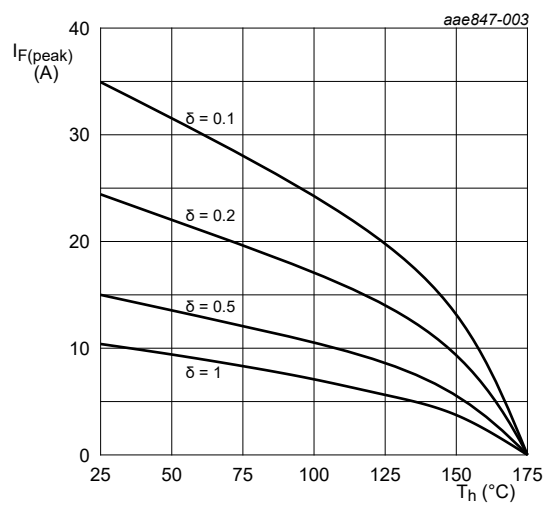


Fig. 4. Current derating as a function of heatsink temperature

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; Fig. 5	-	-	5.3	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W

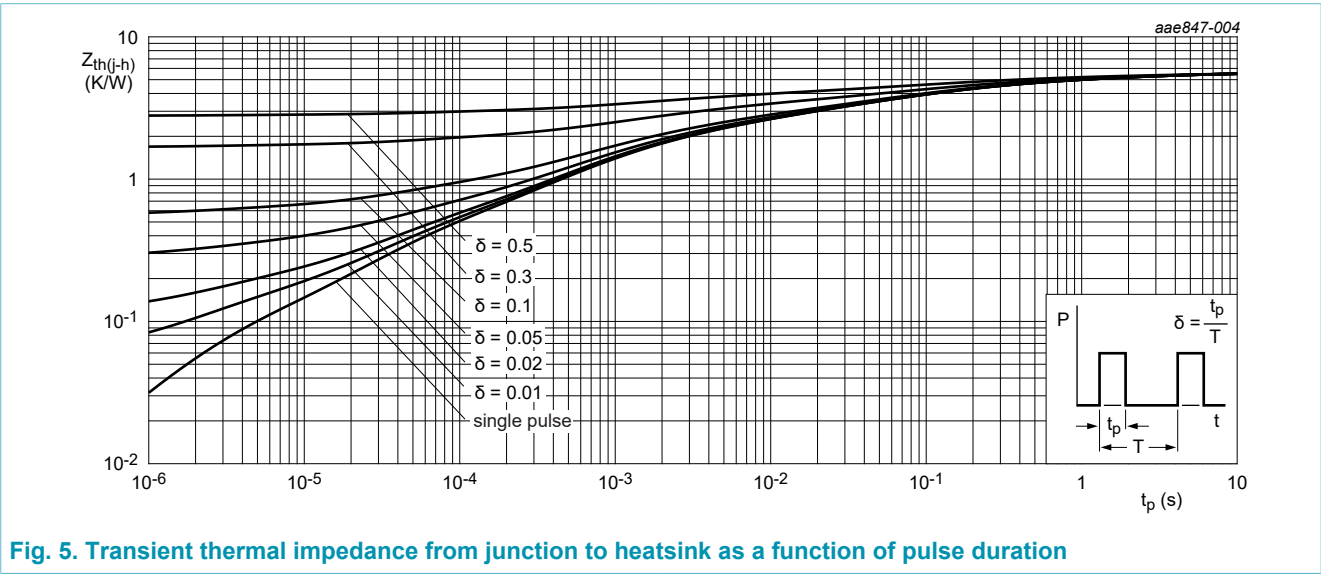


Fig. 5. Transient thermal impedance from junction to heatsink as a function of pulse duration

9. Isolation characteristics

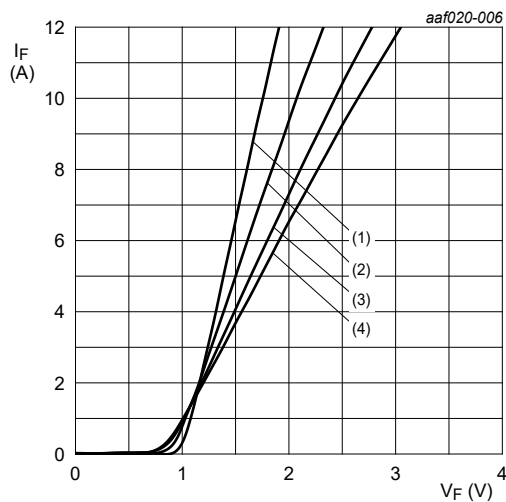
Table 6. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; $50\text{ Hz} \leq f \leq 60\text{ Hz}$ ; $T_h = 25\text{ }^\circ\text{C}$ ; $RH = 65\%$	-	-	2500	V

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 6 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>		-	1.5	1.7	V
		I <sub>F</sub> = 6 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 6</a>		-	1.8	2.1	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C		-	-	200	μA
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 150 °C		-	-	640	μA
Dynamic characteristics							
Q <sub>r</sub>	recovered charge	I <sub>F</sub> = 6 A; dI <sub>F</sub> /dt = 500 A/μs; V <sub>R</sub> = 400 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	10	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C		-	190	-	pF
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>j</sub> = 25 °C		-	23	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	19	-	pF



- (1)  $T_j = 25\text{ °C}$ ; typical values
- (2)  $T_j = 100\text{ °C}$ ; typical values
- (3)  $T_j = 150\text{ °C}$ ; typical values
- (4)  $T_j = 175\text{ °C}$ ; typical values

Fig. 6. Forward current as a function of forward voltage; typical values

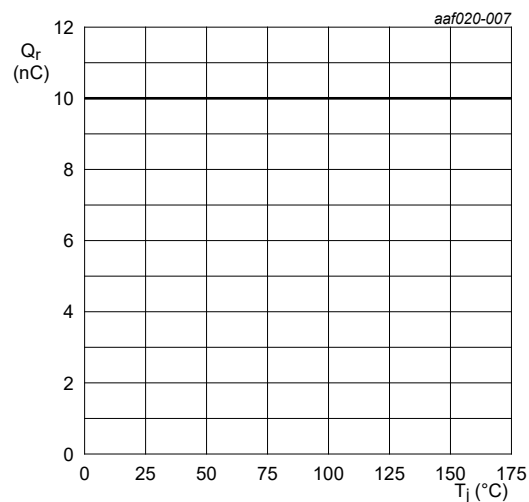
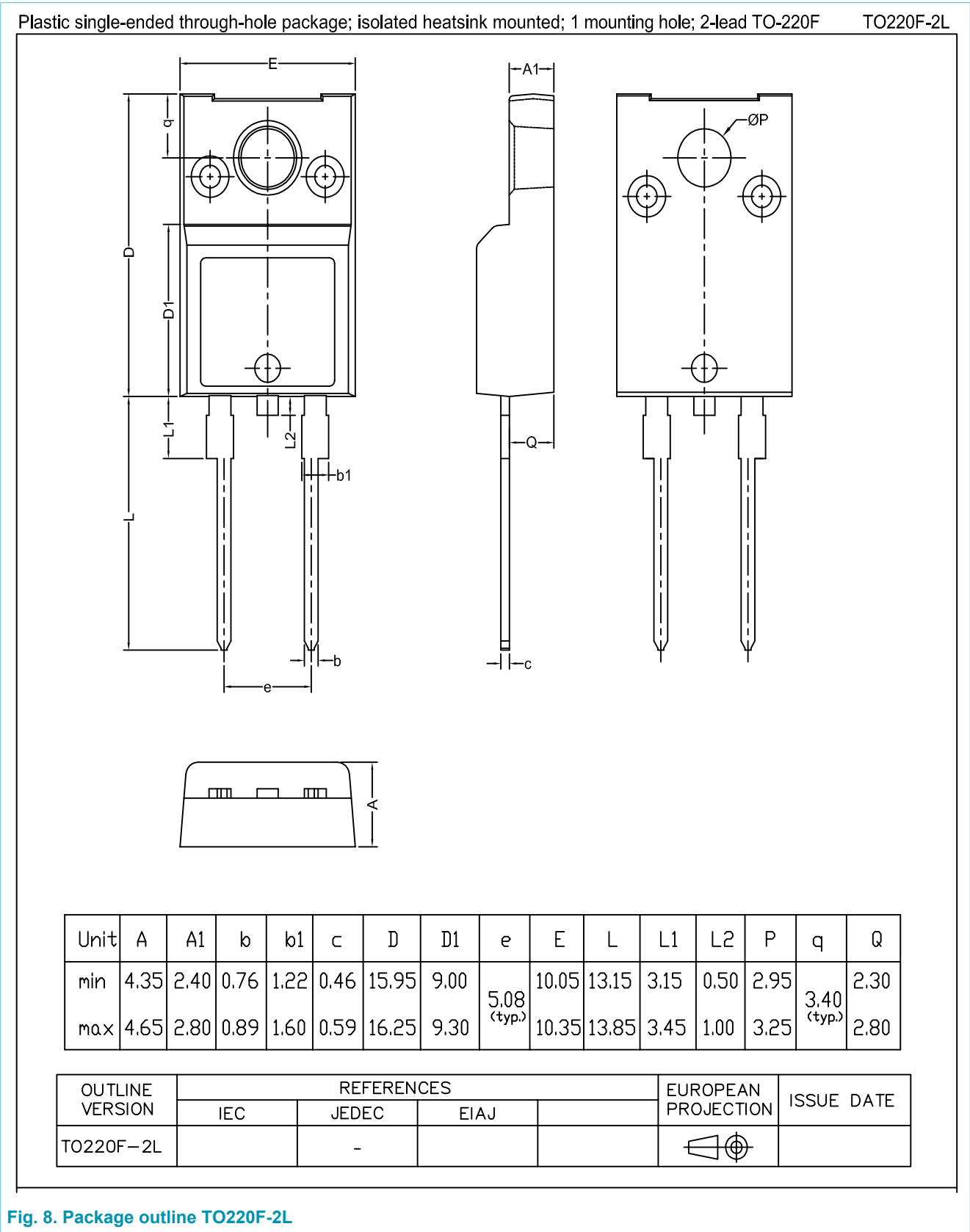


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline



## 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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13. Contents

1. General description..... 1

2. Features and benefits..... 1

3. Applications..... 1

4. Quick reference data..... 1

5. Pinning information.....2

6. Ordering information.....2

7. Limiting values..... 3

8. Thermal characteristics..... 5

9. Isolation characteristics.....5

10. Characteristics.....6

11. Package outline..... 7

12. Legal information..... 8

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Date of release: 5 January 2017



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